LF-370 Conductive copper ink for FR4
Best conductivity in class
The Future of Printed Electronics is Copper.

Copprint enables very-low cost, high conductivity, sustainable printed electronics.

Three key segments:
Printed RFID antennas; Photovoltaics; Flexible electronics
New product: LF-370

Designed for FR-4 substrate:
- Highest conductivity in class
- Excellent durability
- Excellent adhesion
- Simple process
- Solderable
- Hybrid ink – nano and micro copper particles.

Excellent performance also on Alumina and Aluminum

Copprint
Copper inks that outperform Silver
LF-370 – highest conductivity in class

Copprint screen-printing Nano Copper Inks for
a range of substrates:
LF-300 – Paste for paper substrate - Released
LF-350 – paste for PET substrate – Released
LF-370 – paste for FR4 substrate – Released
LF-390 – paste for PI substrate
LF-380 – paste for HJT PV cells
Additional substrates: Alumina, Glass, PC, PEN, CFRP, Tesline

(Average Copprint sintering time: 2-30 seconds)
Really Simple and inexpensive Fabrication

1) Print
Screen printing in few seconds

https://youtu.be/K2W5A1vYA9s

2) Dry
Drying oven/conveyor/UV 1-60 seconds

https://youtu.be/MK7AOaXcjpo

https://youtu.be/K2W5A1vYA9s

3) Sinter
120μ FR4: few sec at 300°C – contactless laminator (Above speed 0.7 meter/min - with 80cm heating element it is 10 meter/min)
1mm FR4: 5-30 sec 280°C-320°C - hotpress
Excellent conductivity, durability and printability

✓ ~2.2mΩ/□/mil
✓ 85-90% solids
✓ Excellent 85/85 performance
✓ Excellent adhesion
✓ Crosshatch test – 5b
✓ Solderability
For more information visit Copprint.com or contact us at Info@Copprint.com